

## **Application Data Sheet**

### **Application Information**

|                          |   |
|--------------------------|---|
| Application Type::       | Regular   |
| Subject Matter::         | Utility   |
| Title::                  | Semiconductor multi-package module having<br>inverted second package stacked over die-down<br>flip-chip ball grid array (BGA) package |
| Attorney Docket Number:: | CPAC 1029-5 D3  |
| Total Drawing Sheets::   | 20  |
| Small Entity?::          | No  |

### **Applicant Information**

|  |                   |
|--|-------------------|
| Applicant Authority Type:              | Inventor          |
| Primary Citizenship Country:           | US                |
| Status:                                | Full Capacity     |
| Given Name:                            | Marcos            |
| Family Name:                           | Karnezos          |
| City of Residence:                     | Palo Alto         |
| State or Province of Residence:        | CA                |
| Country of Residence:                  | US                |
| Street of mailing address:             | 535 Lytton Avenue |
| City of mailing address:               | Palo Alto         |
| State or Province of mailing address:  | CA                |
| Country of mailing address:            | US                |
| Postal or Zip Code of mailing address: | 94301             |

## Correspondence Information

Correspondence Customer Number:: 22470

## Representative Information

|                                  |       |  |
|----------------------------------|-------|--|
| Representative Customer Number:: | 22470 |  |
|----------------------------------|-------|--|

## Domestic Priority Information

| Application::    | Continuity Type::       | Parent Application:: | Parent Filing Date:: |
|------------------|-------------------------|----------------------|----------------------|
| This Application | Non-Provisional of      | 60/417,277           | October 8, 2002      |
| This Application | Non-Provisional of      | 60/460,541           | April 4, 2003        |
| This Application | Continuation-in-Part of | 10/618,933           | July 14, 2003        |
| 10/618,933       | Non-Provisional of      | 60/460,541           | April 4, 2003        |

## Assignee Information

Assignee name:: ChipPAC, Inc.  
Street of mailing address:: 47400 Kato Road  
City of mailing address:: Fremont  
State or Province of mailing address:: CA  
Country of mailing address:: US  
Postal or Zip Code of mailing address:: 94538